

**SEMITOP® 2**

## Bridge Rectifier

### SK 50 B 06 UF

Target Data

### Features

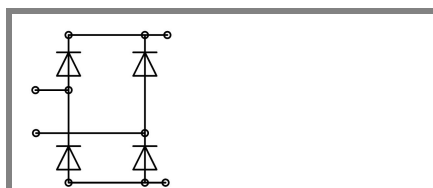
- Compact design
- One screw mounting
- Heat transfer and insulation through direct copper bonded aluminium oxide ceramic (DCB)
- Ultra Fast diodes
- UL recognized, file no. E 63 532

### Typical Applications

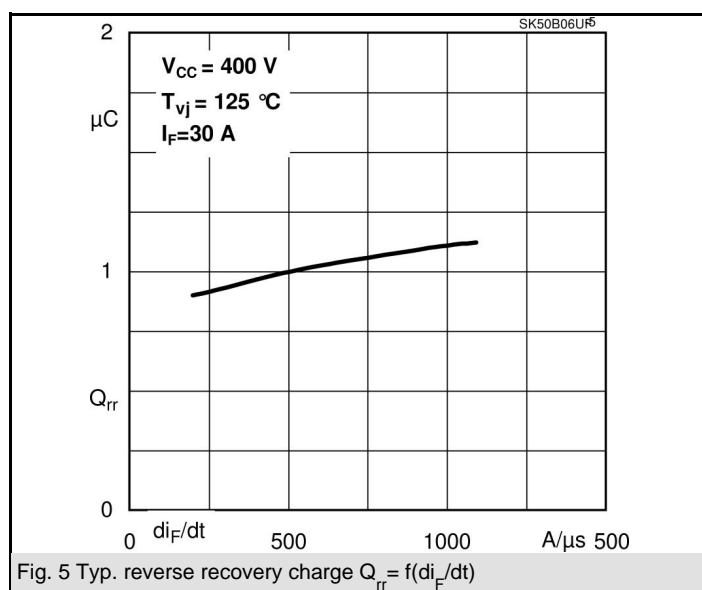
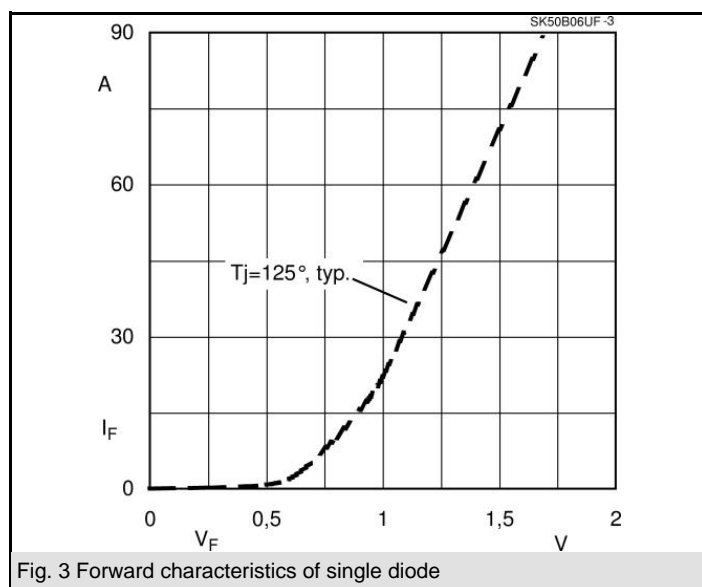
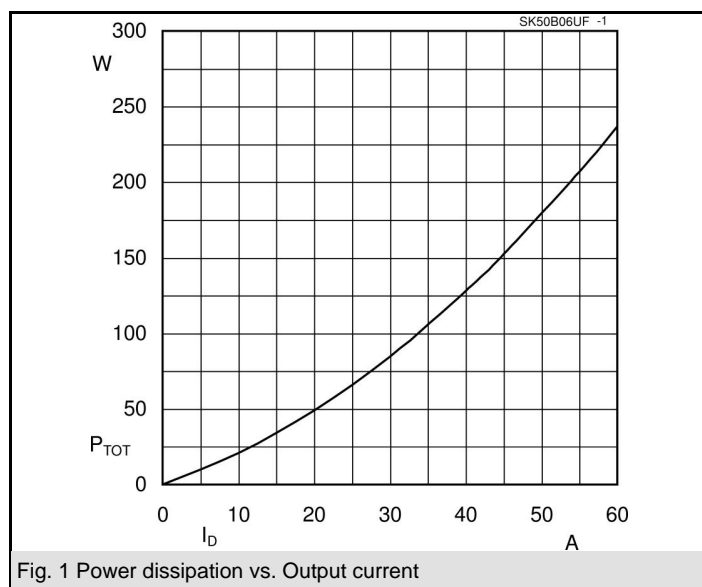
- General power switching applications
- UPS
- SMPS
- Welding equipment

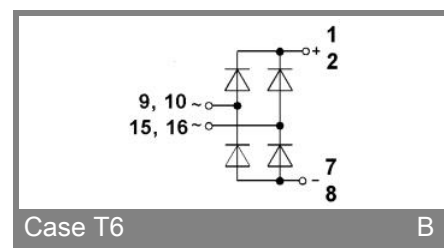
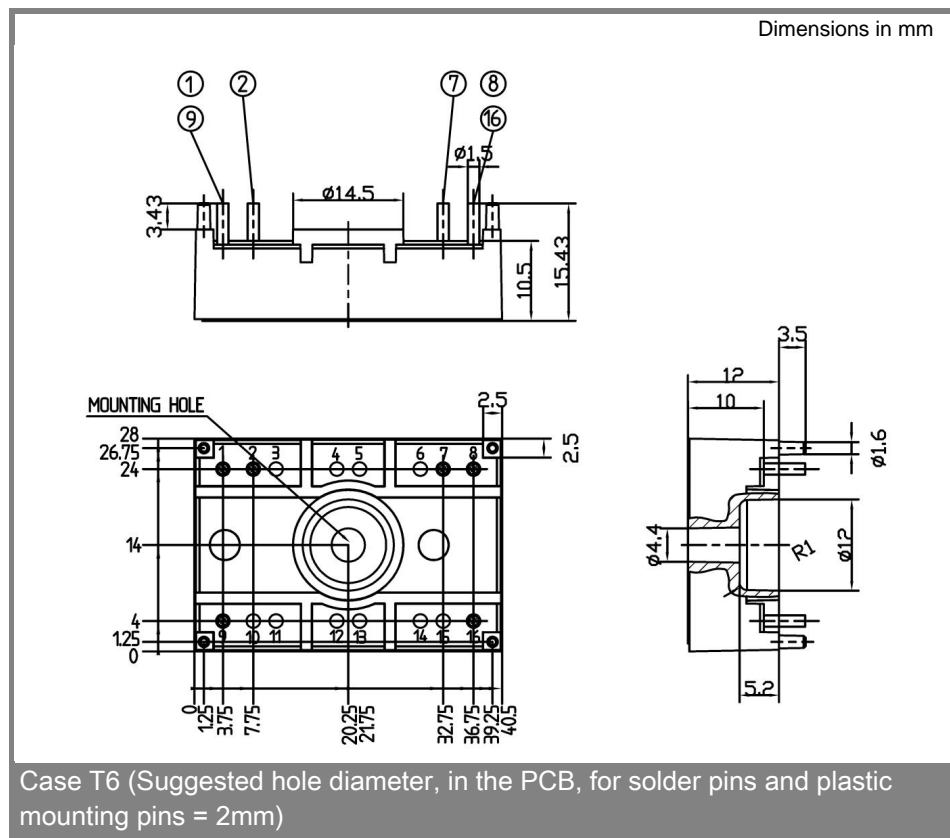
$V_{RSM}$ V	$V_{RRM}, V_{DRM}$ V	$I_D = 46$ A (full conduction) ( $T_s = 80$ °C)
600	600	SK 50 B 06 UF

Symbol	Conditions	Values	Units
$I_D$	$T_s = 80$ °C	46	A
$I_{RRM}$	$T_{vj} = 125$ °C; $V_R = 400$ V; $I_F = 30$ A;	11	A
$Q_{rr}$	$-di_F/dt = 300$ A/μs	typ. 0,93	μC
$I_R$	$T_{vj} = 25$ (150) °C; $V_R = V_{RRM}$	max 0,015 (0,475)	mA
$I_{FSM}$	$T_{vj} = 150$ °C; 10 ms	400	A
$i^2t$	$T_{vj} =$ °C; ms	800	A²s
	$T_{vj} = 150$ °C; 10 ms		A²s
	$T_{vj} =$ °C; ms		
$V_F$	$T_{vj} = 125$ °C; $I_F = 50$ A	max. 1,95	V
$V_{(TO)}$	$T_{vj} = 125$ °C	max. 0,8	V
$r_T$	$T_{vj} = 125$ °C	max. 11	mΩ
$I_{RD}$	$T_{vj} =$ °C; $V_{DD} = V_{DRM}$ ; $V_{RD} = V_{RRM}$		mA
			mA
$R_{th(j-s)}$	per diode	1,8	K/W
	per module	0,45	K/W
$T_{solder}$	terminals, 10s	260	°C
$T_{vj}$		-40...+150	°C
$T_{stg}$		-40...+125	°C
$V_{isol}$	a. c. 50 Hz; r.m.s.; 1 s / 1 min.	3000 ( 2500 )	V
$M_s$	mounting torque to heatsink	2	Nm
$M_t$			
$m$	approx. weight	19	g
Case	SEMITOP® 2	T 6	



**B**





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